

TC74HC112AP, TC74HC112AF, TC74HC112AFN

DUAL J-K FLIP-FLOP WITH PRESET AND CLEAR

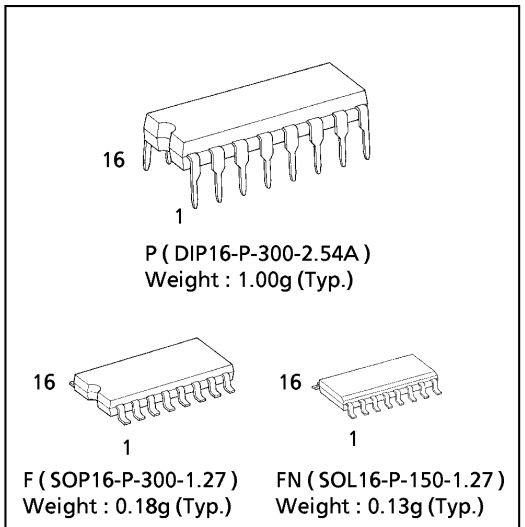
The TC74HC112A is a high speed CMOS DUAL J-K FLIP FLOP fabricated with silicon gate C²MOS technology. It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation. In accordance with the logic levels applied to the J and K inputs, the outputs change state on the negative going transition of the clock pulse.

$\overline{\text{CLR}}$ and $\overline{\text{PR}}$ are independent of the clock and are actived by a low logic level on the corresponding input. All inputs are equipped with protection circuits against static discharge or transient excess voltage.

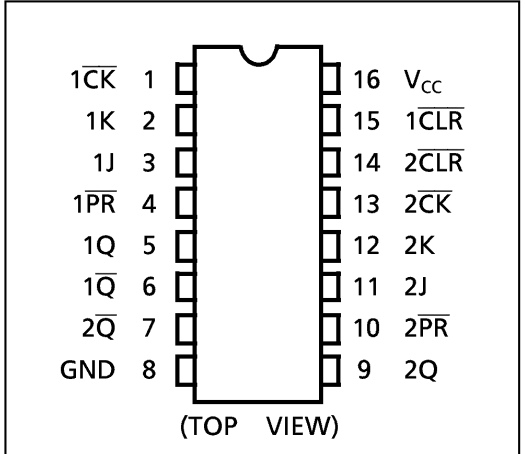
FEATURES:

- High Speed..... $f_{\text{MAX}} = 67\text{MHz}$ (typ.)
at $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 2\mu\text{A}$ (Max.) at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}}$ (Min.)
- Output Drive Capability..... 10 LSTTL Loads
- Symmetrical Output Impedance... $|I_{\text{OH}}| = I_{\text{OL}} = 4\text{mA}$ (Min.)
- Balanced Propagation Delays..... $t_{\text{PLH}} \approx t_{\text{PHL}}$
- Wide Operating Voltage Range... V_{CC} (opr.) = 2V~6V
- Pin and Function Compatible with 74LS112

(Note) The JEDEC SOP (FN) is not available in Japan.



PIN ASSIGNMENT

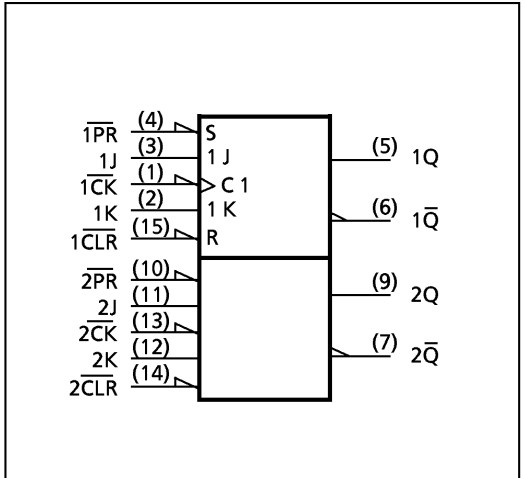


TRUTH TABLE

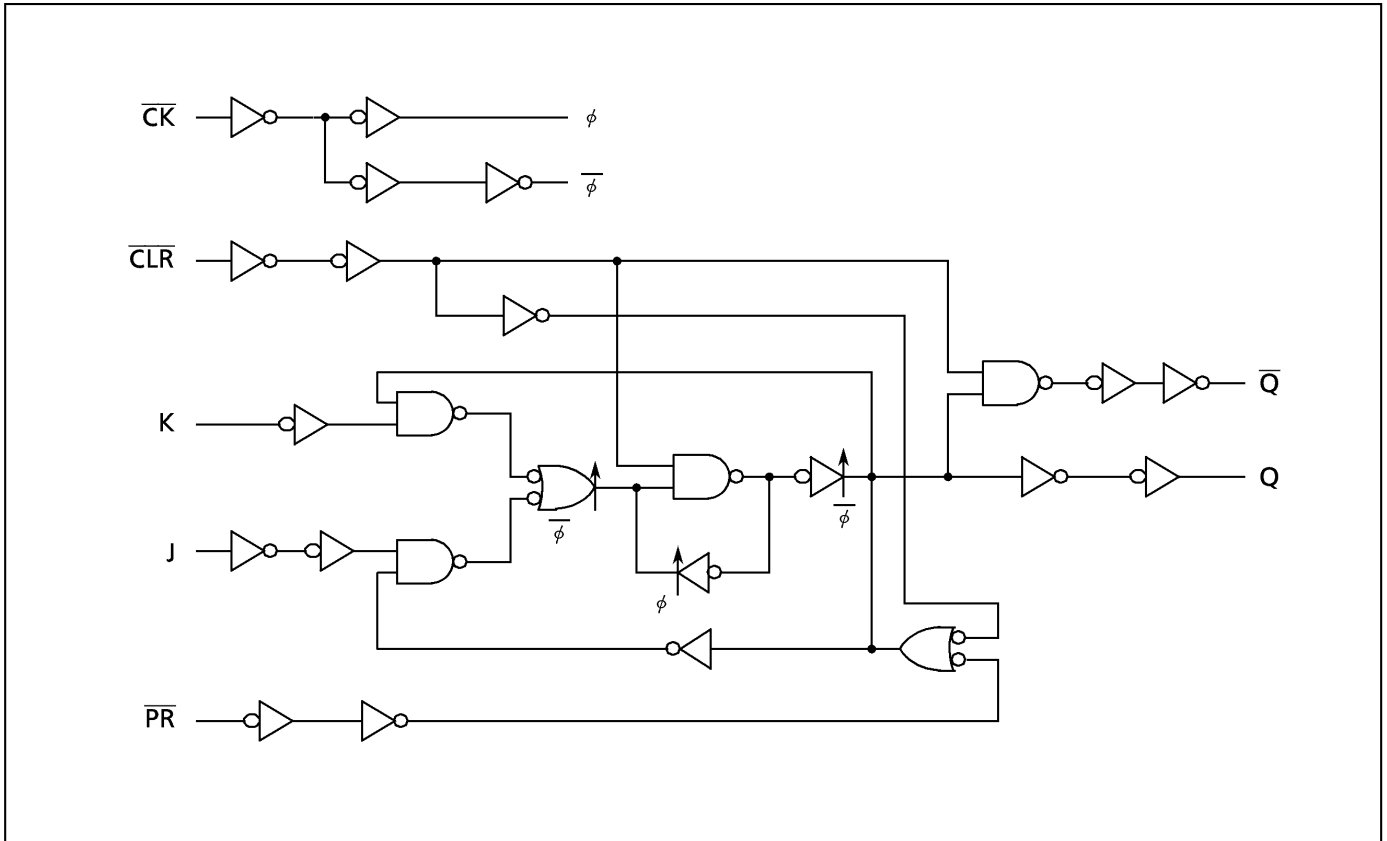
INPUTS					OUTPUTS		FUNCTION
$\overline{\text{CLR}}$	$\overline{\text{PR}}$	J	K	$\overline{\text{CK}}$	Q	$\overline{\text{Q}}$	
L	H	X	X	X	L	H	CLEAR
H	L	X	X	X	H	L	PRESET
L	L	X	X	X	H	H	
H	H	L	L	\downarrow	Q_n	\overline{Q}_n	NO CHANGE
H	H	L	H	\downarrow	L	H	
H	H	H	L	\downarrow	H	L	
H	H	H	H	\downarrow	\overline{Q}_n	Q_n	TOGGLE
H	H	X	X	\uparrow	Q_n	\overline{Q}_n	NO CHANGE

X : Don't Care

IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 25	mA
DC V_{CC} / Ground Current	I_{CC}	± 50	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	$^{\circ}\text{C}$

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	$2 \sim 6$	V
Input Voltage	V_{IN}	$0 \sim V_{CC}$	V
Output Voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating Temperature	T_{opr}	$-40 \sim 85$	$^{\circ}\text{C}$
Input Rise and Fall Time	t_r, t_f	$0 \sim 1000 (V_{CC} = 2.0\text{V})$ $0 \sim 500 (V_{CC} = 4.5\text{V})$ $0 \sim 400 (V_{CC} = 6.0\text{V})$	ns

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	$T_a = 25^{\circ}\text{C}$			$T_a = -40 \sim 85^{\circ}\text{C}$		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	V_{IH}		2.0	1.50	—	—	1.50	—	V	
			4.5	3.15	—	—	3.15	—		
			6.0	4.20	—	—	4.20	—		
Low - Level Input Voltage	V_{IL}		2.0	—	—	0.50	—	0.50	V	
			4.5	—	—	1.35	—	1.35		
			6.0	—	—	1.80	—	1.80		
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -20\mu\text{A}$	2.0	1.9	2.0	—	1.9	—	V
				4.5	4.4	4.5	—	4.4	—	
		$I_{OH} = -4 \text{ mA}$ $I_{OH} = -5.2 \text{ mA}$	4.5	4.18	4.31	—	4.13	—		
			6.0	5.68	5.80	—	5.63	—		
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 20\mu\text{A}$	2.0	—	0.0	0.1	—	0.1	V
				4.5	—	0.0	0.1	—	0.1	
		$I_{OL} = 4 \text{ mA}$ $I_{OL} = 5.2 \text{ mA}$	4.5	—	0.17	0.26	—	0.33		
			6.0	—	0.18	0.26	—	0.33		
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	± 0.1	—	± 1.0	μA	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	2.0	—	20.0		

TIMING REQUIREMENTS (Input $t_r = t_f = 6ns$)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C		Ta = -40~85°C	UNIT
				TYP.	LIMIT	LIMIT	
Minimum Pulse Width (\overline{CK})	$t_{W(L)}$ $t_{W(H)}$		2.0	—	75	95	ns
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Pulse Width (\overline{CLR} , \overline{PR})	$t_{W(L)}$		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Set-up Time	t_s		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Hold Time	t_h		2.0	—	0	0	
			4.5	—	0	0	
			6.0	—	0	0	
Minimum Removal Time (\overline{CLR} , \overline{PR})	t_{rem}		2.0	—	50	60	
			4.5	—	10	12	
			6.0	—	9	11	
Clock Frequency	f		2.0	—	6	4	MHz
			4.5	—	30	24	
			6.0	—	34	28	

AC ELECTRICAL CHARACTERISTICS (C_L = 15pF, V_{CC} = 5V, Ta = 25°C, Input $t_r = t_f = 6ns$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t_{TLH} t_{THL}		—	4	8	ns
Propagation Delay Time ($\overline{CK}-Q$, \overline{Q})	t_{pLH} t_{pHL}		—	13	21	
Propagation Delay Time (\overline{CLR} , $\overline{PR}-Q$, \overline{Q})	t_{pLH} t_{pHL}		—	15	22	
Maximum Clock Frequency	f_{MAX}		32	67	—	MHz

AC ELECTRICAL CHARACTERISTICS (C_L = 50pF, Input $t_r = t_f = 6ns$)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	t_{TLH} t_{THL}		2.0	—	30	75	—	95	ns
			4.5	—	8	15	—	19	
			6.0	—	7	13	—	16	
Propagation Delay Time ($\overline{CK}-Q$, \overline{Q})	t_{pLH} t_{pHL}		2.0	—	52	125	—	155	
			4.5	—	16	25	—	31	
			6.0	—	14	21	—	26	
Propagation Delay Time (\overline{CLR} , $\overline{PR}-Q$, \overline{Q})	t_{pLH} t_{pHL}		2.0	—	68	135	—	170	
			4.5	—	17	27	—	34	
			6.0	—	15	23	—	29	
Maximum Clock Frequency	f_{MAX}		2.0	6	19	—	4	—	MHz
			4.5	30	63	—	24	—	
			6.0	34	71	—	28	—	
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Power Dissipation Capacitance	C _{PD} (1)			—	35	—	—	—	

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC}(opr) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 2 \text{ (per F/F)}$$

DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)

Unit in mm



Weight : 1.00g (Typ.)

SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)

Unit in mm



Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

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